

Dry Etching Agent for Semiconductors HFC-32(CH₂F₂)

TECHNICAL
DATASHEET

The dry etching agent HFC-32(CH₂F₂) is a high purity etching gas for use in semiconductor manufacturing.

Introduction

- Purity is 99.99vol% (4N) or more for semiconductor manufacturing.
- Mainly suitable for etching SiO₂, SiN and low-k films.

General physical properties

Items	Unit	Numeric Value
Molecular formula	-	CH ₂ F ₂
Molecular weight	-	52.02
Boiling point	°C	-51.7
Vapor pressure(20°C)	MPa	1.39

Inspection Items

- Purity (excluding air content), other fluorocarbons, acid content, moisture, air content

Please contact us for details on the quality levels of individual items.

Handling method/Safety information

- Be sure to read the notes on SDS and labels before use.
- This product has been developed for industrial purposes and we shall not guarantee the safety if used for any other purposes. If it is going to be used for medical or food applications, please contact us in advance.

Packing specification

- 10L container, 47L container, etc.

For more information, visit our website.

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